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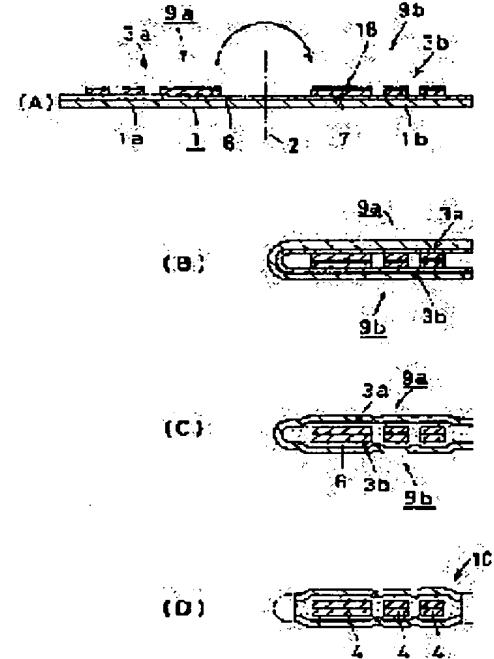
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(54) FLEXIBLE PRINTED CIRCUIT BOARD AND MANUFACTURE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain an FPC(flexible printed circuit board) which can be made small in size by narrowing the pattern width.

SOLUTION: A band-like base film 1 is divided into left and right bases 1a and 1b pinching a bend line 2 at the center of widthwise direction, circuit patterns 3a and 3b, which make a left and right symmetrical shape, are formed thereon, and a pair of substrate constituent members 9a and 9b are formed. Both substrate constituent members 9a and 9b are bent at the bend line 2, the surface of both substrate constituent members 9a and 9b are superposed while both circuit patterns 3a and 3b are being aligned. When both superposed substrate constituent members 9a and 9b are press-molded under the state of heating, both substrate constituent members 9a and 9b are integrally formed in the state wherein the opposing parts of both circuit patterns 3a and 3b are superposed with each other. Lastly, external shape is punched out, and an FPC 10, having each pattern 4 in double thickness, is completed.



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